# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

### Marketing Name / Model
[List multiple models if applicable.]

| HP ProDesk 400 G1  Small Form Factor Business PC |

### Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1. **Items Requiring Selective Treatment**
   1.1 Items listed below are classified as requiring selective treatment.
   1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Acbel EPA85</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Loose the screw and remove access panel.(see Figure 1 below)
2. Rotate the driver cage form the hook on slide rail.(see Figure 2 below)
3. Disconnect SATA cables from the MB.(see Figure 3 below)
4. Disconnect other PSU cables from the MB.(see Figure 4-9 below)
5. Remove HDD/ODD from chassis.(see Figure 10-18 below)
6. Remove the heatsink from MB.(see Figure19-21 below)
7. Separate the fan from CPU heatsink. (see Figure 22-23 below)
8. Remove the CPU from the MB.(see Figure 24-25 below)
9. Remove the Memory card from the MB.(see Figure 26 below)
10. Remove the battery from the MB.(see Figure 27 below)
11. Remove M/B from chassis.(see Figure 28-29 below)
12. Remove front panel from chassis.(see Figure 30 below)
13. Remove FIO/Speaker/LED holder from chassis.(see Figure 31-33 below)
14. Remove PSU cover.(see Figure 34-40 below)
15. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 41-44 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1: Loose the screw and remove access panel.

Figure 2: Rotate the driver cage from the hook on slide rail.

Figure 3: Disconnect SATA cables from the MB.

Figure 4: Disconnect FIO cables from MB.

Figure 5: Disconnect Speaker cable from the MB.

Figure 6: Disconnect ODD/HDD PSU cables from the MB.

PSG instructions for this template are available at [EL-MF877-01](#).
Figure 7 Disconnect MB PSU cable from the MB
Figure 8 Disconnect other PSU cables from the MB
Figure 9 Disconnect CPU Power cable from the MB
Figure 10 Disconnect HDD Power cable from HDD
Figure 11 Disconnect SATA cable from HDD
Figure 12 Remove the cables from the chassis clip

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 13 Press the HDD’s latch on HDD cage

Figure 14 Remove the HDD from HDD cage

Figure 15 Disconnect ODD power cable from ODD

Figure 16 Disconnect SATA cable from ODD

Figure 17 Press the ODD’s latch on ODD cage

Figure 18 Remove the ODD from ODD cage

PSG instructions for this template are available at EL-MF877-01
Figure 19 Remove the Heatsink PSU cable from MB

Figure 20 Rotate the Fan duct and remove it

Figure 21 Loose the screws and remove heat sink

Figure 22 Loose the screws and remove heatsink fan

Figure 23 Separate the fan from CPU heatsink

Figure 24 Rotate the handle and open it up
<table>
<thead>
<tr>
<th>Figure 25</th>
<th>Figure 26</th>
</tr>
</thead>
<tbody>
<tr>
<td>Remove the CPU from the board</td>
<td>Remove the Memory card from the board</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 27</th>
<th>Figure 28</th>
</tr>
</thead>
<tbody>
<tr>
<td>Remove the battery from the system board</td>
<td>Loose the screws of MB from board</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 29</th>
<th>Figure 30</th>
</tr>
</thead>
<tbody>
<tr>
<td>Remove M/B from chassis</td>
<td>Remove front panel from chassis</td>
</tr>
</tbody>
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PSG instructions for this template are available at [EL-MF877-01](#)
Figure 31 Loose the screws of FIO and remove it

Figure 32 Loose the screws of speaker and remove it

Figure 33 Remove the holder of LED power cable from chassis

Figure 34 Remove the screws on the PSU chassis

Figure 35 Press the PSU's latch on chassis

Figure 36 Remove the Power supply from chassis

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 37 Remove screw for top

Figure 38 Remove screw for bottom

Figure 39 Remove screw for front

Figure 40 Remove the screw and open case

When removed only PCBA left

Figure 41 Disconnect the cable-wire from product

Figure 42 Loose the screw of PCBA cable

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 43 When removed only PCBA left

Figure 44 Show Ele-Cap on PCBA

PSG instructions for this template are available at [EL-MF877-01](#)